

Method of Providing for an Automated Split Runcard Processing

ABSTRACT OF THE DISCLOSURE

A method of providing fully automated processing of a Split Lot of wafers to manufacture semiconductor devices is provided. The method processes a test Lot of wafers with a production Lot. Processing of both Lots continue as a single Lot along the production processing path up to a split condition process. Processing of the production Lot is put on hold until the alternate processing or test Lot processing is completed. The two Lots are then merged and processed according to the original predefined process steps continue on both Lots.

FIG. 1